



February 16, 2017

Invensas Announces Teledyne DALSA Signs DBI Technology Transfer and License Agreement

Revolutionary Wafer Bonding and 3D Interconnect Technology To Enable Delivery Of Next-Generation MEMS and Image Sensor Solutions

SAN JOSE, Calif.--(BUSINESS WIRE)-- Invensas Corporation, a wholly owned subsidiary of Tessera Holding Corporation (Nasdaq:TSRA), today announced that Teledyne DALSA, a Teledyne Technologies company, has signed a technology transfer and license agreement for Direct Bond Interconnect (DBI[®]) technology. This agreement enables Teledyne DALSA to leverage Invensas' revolutionary semiconductor wafer bonding and 3D interconnect technologies to deliver next-generation MEMS and image sensor solutions to customers in the automotive, IoT and consumer electronics markets. Teledyne DALSA is an international leader in high performance digital imaging and semiconductors and also one of the world's foremost pure-play MEMS foundries.

"DBI technology is a key enabler for true 3D-integrated MEMS and image sensor solutions," said Edwin Roks, president of Teledyne DALSA. "We are excited about the prospect of developing new products and providing new foundry services to our customers that utilize this technology. By working closely with Invensas, we will be able to move more quickly to deploy this capability efficiently and effectively."

DBI technology is a low temperature hybrid wafer bonding solution that allows wafers to be bonded instantaneously with exceptionally fine pitch 3D electrical interconnect without requiring bond pressure. The technology is applicable to a wide range of semiconductor devices including MEMS, image sensors, RF Front Ends and stacked memory.

"We are pleased that Teledyne DALSA, a recognized leader in digital imaging products and MEMS solutions, has chosen our DBI technology to accelerate the development and commercialization of their next generation MEMS and image sensor products," said Craig Mitchell, president of Invensas. "As device makers look for increasingly powerful semiconductor solutions in smaller packages, the need for cost-efficient, versatile 3D technologies is greater than ever before. We are confident that the superior performance and manufacturability of DBI technology will help Teledyne DALSA deliver tremendous value to their customers."

For more information on DBI technology and other advanced semiconductor packaging and interconnect solutions from Invensas, please visit www.invensas.com.

About Tessera Holding Corporation

Tessera Holding Corporation is the parent company of DTS, FotoNation, Invensas and Tessera. We are one of the world's leading product and technology licensing companies. Our technologies and intellectual property are deployed in areas such as premium audio, computational imaging, computer vision, mobile computing and communications, memory, data storage, 3D semiconductor interconnect and packaging. We invent smart sight and sound technologies that enhance and help to transform the human connected experience.

For more information, call +1 408-321-6000 or visit www.tesseractholdingcorporation.com.

About Teledyne DALSA

Teledyne DALSA is an international technology leader in sensing, imaging, and specialized semiconductor fabrication. Our image sensing solutions span the spectrum from infrared through visible to X-ray; our MEMS foundry has earned a world-leading reputation. In addition, through our subsidiaries Teledyne Optech and Teledyne Caris, we deliver advanced 3D survey and geospatial information systems. Teledyne DALSA employs approximately 1,400 employees worldwide and is headquartered in Waterloo, Canada. For more information, visit www.teledynedalsa.com.

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Forward-Looking Statements

This press release contains forward-looking statements, which are made pursuant to the safe harbor provisions of the Private Securities Litigation Reform Act of 1995. Forward-looking statements involve risks and uncertainties that could cause actual results to differ significantly from those projected, particularly with respect to the expected benefits of the cooperation agreement, plans with respect to other markets and the expected first uses of the initial deployment. Material factors that may cause results to differ from the statements made include the plans or operations relating to the businesses of the Company; market or industry conditions; changes in patent laws, regulation or enforcement, or other factors that might affect the Company's ability to protect or realize the value of its intellectual property; the expiration of license agreements and the cessation of related royalty income; the failure, inability or refusal of licensees to pay royalties; initiation, delays, setbacks or losses relating to the Company's intellectual property or intellectual property litigations, or invalidation or limitation of key patents; fluctuations in operating results due to the timing of new license agreements and royalties, or due to legal costs; the risk of a decline in demand for semiconductors and products utilizing FotoNation technologies; failure by the industry to use technologies covered by the Company's patents; the expiration of the Company's patents; the Company's ability to successfully complete and integrate acquisitions of businesses; the risk of loss of, or decreases in production orders from, customers of acquired businesses; financial and regulatory risks associated with the international nature of the Company's businesses; failure of the Company's products to achieve technological feasibility or profitability; failure to successfully commercialize the Company's products; changes in demand for the products of the Company's customers; limited opportunities to license technologies due to high concentration in the markets for semiconductors and related products; the impact of competing technologies on the demand for the Company's technologies; failure to realize the anticipated benefits of the Company's recent acquisition of DTS, Inc., including as a result of integrating the business of DTS; pricing trends, including the Company's ability to achieve economies of scale; the expected amount and timing of cost savings and operating synergies; and other developments in the markets that the Company operates, as well as management's response to any of the aforementioned factors. You are cautioned not to place undue reliance on the forward-looking statements, which speak only as of the date of this release.

The foregoing review of important factors should not be construed as exhaustive and should be read in conjunction with the other cautionary statements that are included herein and elsewhere, including the Risk Factors included in the Company's recent reports on Form 10-K and Form 10-Q and other documents of the Company on file with the Securities and Exchange Commission (the "SEC"). The Company's SEC filings are available publicly on the SEC's website at www.sec.gov. Any forward-looking statements made or incorporated by reference herein are qualified in their entirety by these cautionary statements, and there can be no assurance that the actual results or developments anticipated by the Company will be realized or, even if substantially realized, that they will have the expected consequences to, or effects on, the Company or its business or operations. Except to the extent required by applicable law, the Company undertakes no obligation to update publicly or revise any forward-looking statement, whether as a result of new information, future developments or otherwise.

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Source: Tessera Holding Corporation

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